

# Mighty Tracker: HV-MAPS @ LHCb UII

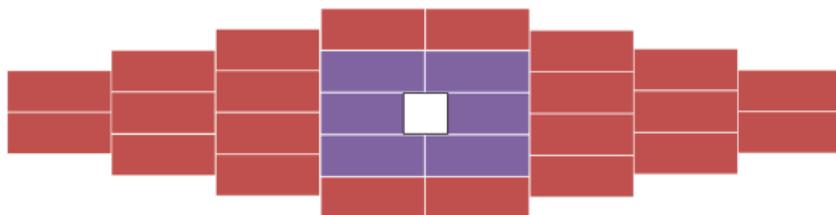
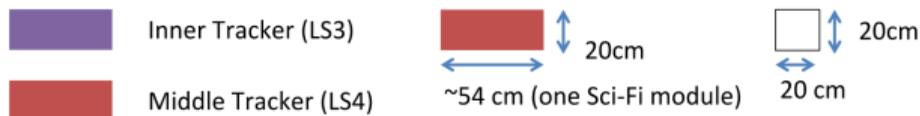
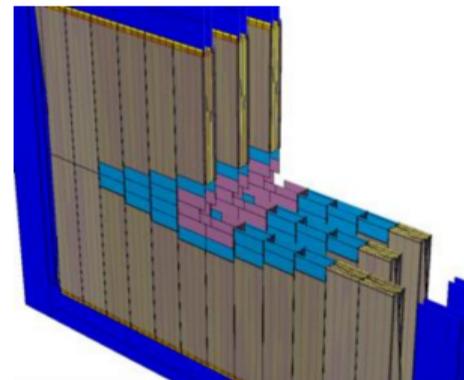
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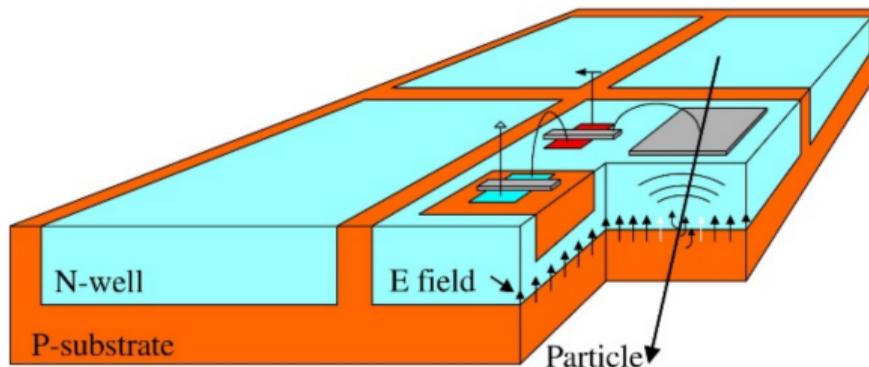
PixLab Meeting - 4<sup>th</sup> May 2020

- Proposed LHCb upstream tracker after Upgrade II.
- Silicon sensors counteract SciFi limitations in terms of radiation damage and maximum occupancy.
- Time measurement not expected to be required.
- Readout and services integrated in SciFi module.

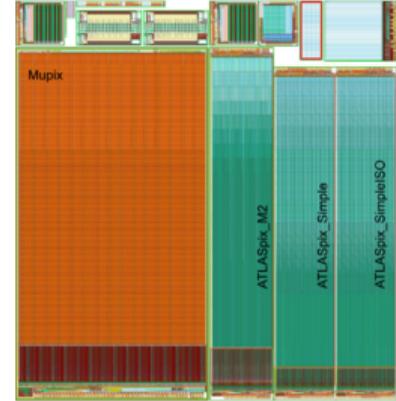
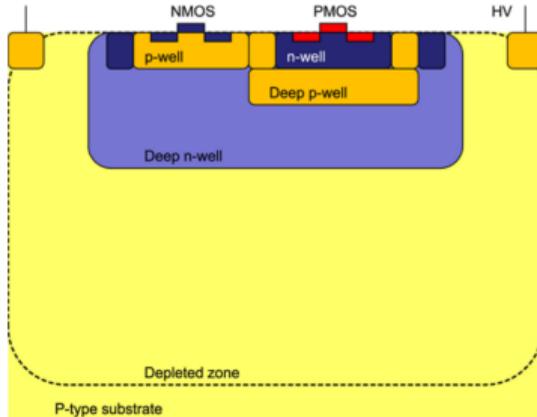


- Cover 18(4)m<sup>2</sup> after LS4(3).
- Only 6 layers required.
- MT receives ~50% tracks.
- Up to 415 Gbps per layer.
- Maximum expected fluence  $3 \times 10^{14}$  1 MeV neq/cm<sup>2</sup>.

- Initially silicon strips sensors were also contemplated but HV-DMAPS pixel sensors were always the baseline option.
- Several technologies of HV-MAPS were originally studied:
  - collaboration has experience and mature solutions with AMS/TSI 180nm,
  - solutions with Lfoundries 150nm are also suitable but not so advanced,
  - TowerJazz improves power consumption but unknown radiation tolerance.
- Latest version of MuPix/ATLASPix used as reference for specifications.

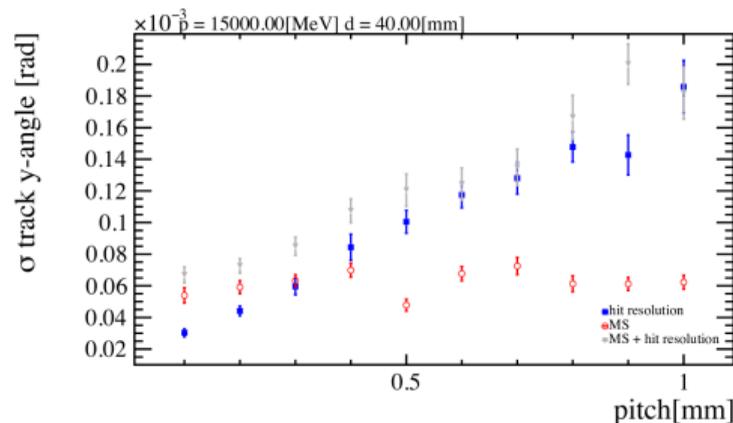
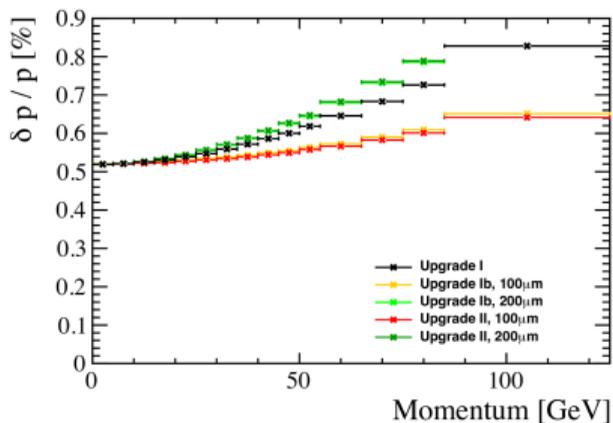


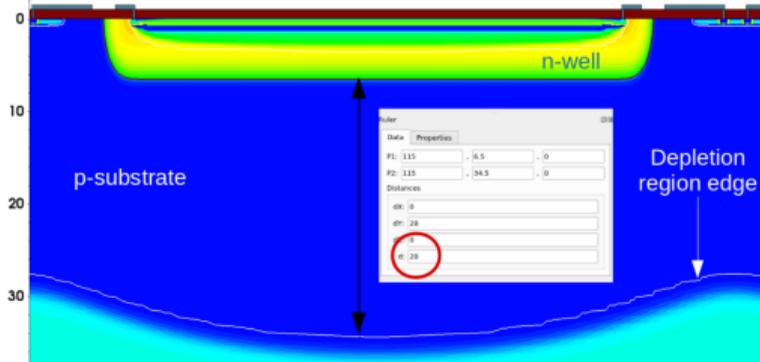
- The design will be developed in TSI 180nm technology, allowing synergy (dsgn&mfg) with MuPix/ATLASPix.
- Chip area (~2cmx2cm) limited by TSI reticle size.
- Aiming at large fill factor device with <5% dead area (guardring + dicing 100μm, but dominated by periphery).



- TSI HV process layer map includes triple well, which offers additional design options.
- TSI HV process offers high resistivity wafers, which enlarges depletion region.

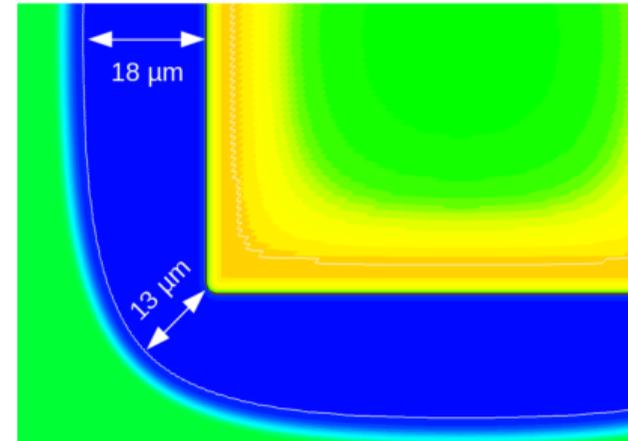
- Baseline size  $100\mu\text{m}\times 300\mu\text{m}$  considering down to  $50\mu\text{m}\times 150\mu\text{m}$ .
  - Horizontally  $100\mu\text{m}$  assures LHCb UI momentum resolution.
  - Vertically, under  $300\mu\text{m}$  multiple scattering dominates resolution over pixel size.
- Baseline can increase capacitance a factor 2 with respect to current devices taking a big toll on power consumption and/or time-walk dispersion.
- Smaller pixel size with logical sum included in readout is also considered.



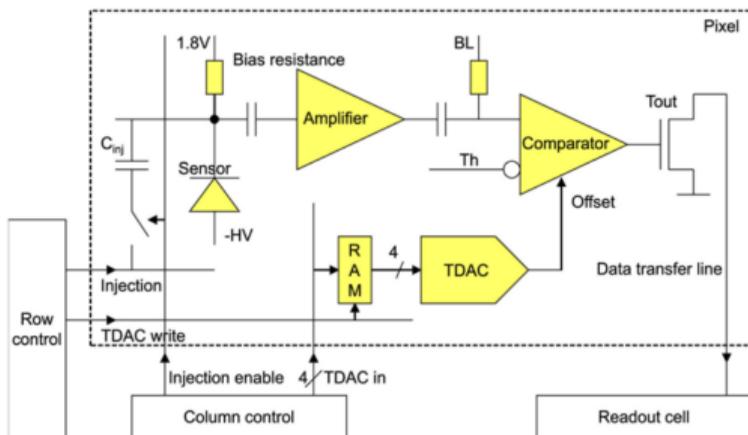


- Sensor thickness set at 200 $\mu\text{m}$ , analogue by size to ATLASPix (50 $\mu\text{m}$  $\times$ 150 $\mu\text{m}$  $\times$ 250 $\mu\text{m}$ ).
- TCAD yields  $\sim$ 30 $\mu\text{m}$  depletion region for 60V bias and 200 $\Omega\text{cm}$  wafer.

- Charge deposit in 4 $\mu\text{m}$  radius cylinder.
- Geometrically 98% of single cell clusters, other effects still have to be considered. (delta-rays, cross-coupling ...)
- Further studies in lateral growth and corners to assure full depletion in whole matrix.

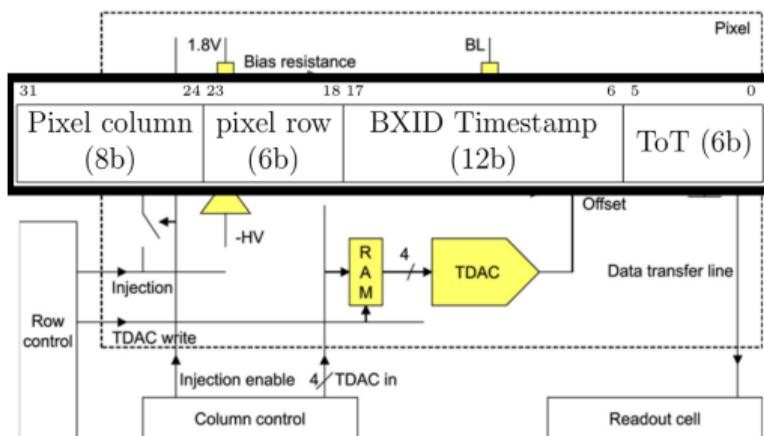


- Pixel would include bias resistor, amplifier and comparator (no design yet).
- Voltage (source follower) and current (current driver) amplifiers available, also nMOS exclusive and CMOS comparators (in-pixel and periphery).
- Radiation tolerance enhanced by enclosed transistor and low drift length.



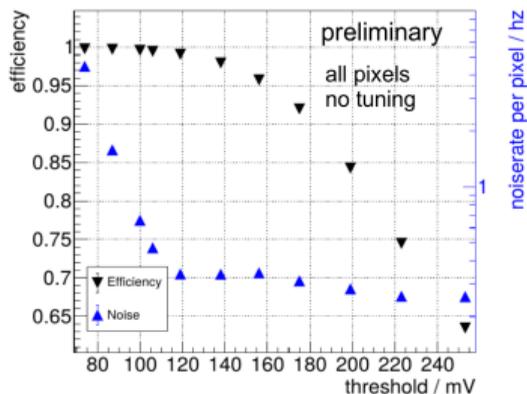
- Hit efficiency  $>99\%$
- Noise  $<30\text{Hz}/\text{px}$  (1% avg data rate)
- Power  $<150\text{mW}/\text{cm}^2$
- Time resolution  $<3\text{ns}$  ( $4\sigma$  in 25ns)
- Total ionizing dose  $<40\text{MRad}$
- N fluence  $<6 \times 10^{14}$  1 MeV neq/cm<sup>2</sup>
- Output data rate 4x1.28Gbps

- Continuous readout with timestamp per hit to avoid on-chip descramble, ToT for time walk correction and 8b10b encoding for DC-balance.
- Assuming 1.7 events per chips, maximum data rate below 2.5Gbps.
- Optical interface through IpGBT with experiment readout and control systems.

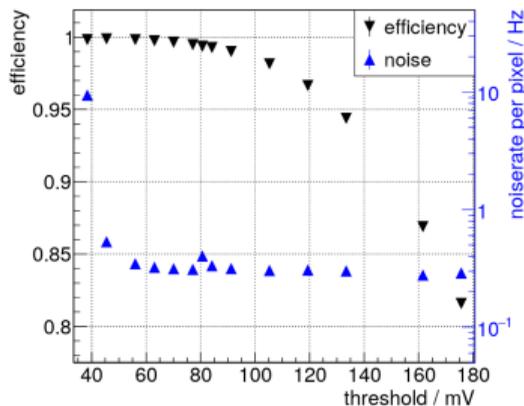


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- High efficiency and low noise overlap in all devices.
- Migration to TSI successful.
- Wafer resistivity effect apparent.

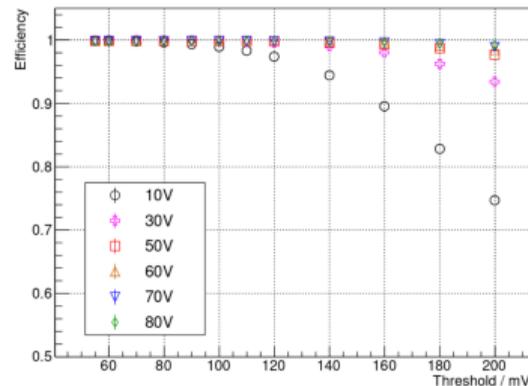


ATLASPix3  
TSI 180nm  
80Ωcm??



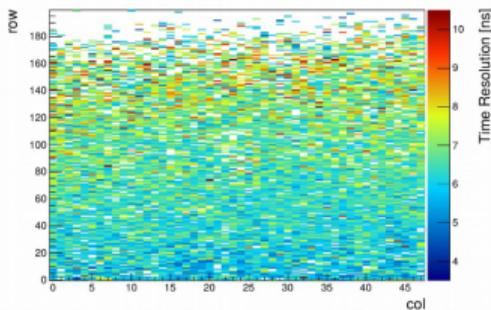
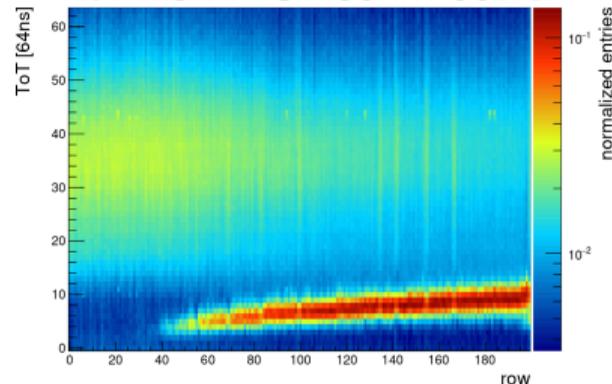
MuPix8  
AMS 180nm  
80Ωcm

ATLASPix1  
AMS 180nm  
200Ωcm

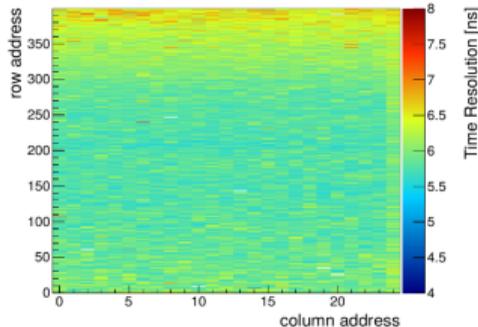


- Time resolution  $\sim 6\text{ns}$  in all devices after time walk correction with ToT.
- MuPix8 uses periphery comparators, cross-coupling affects ToT measurement.
- ATLASPix1 intrinsic resolution below  $4\text{ns}$ .

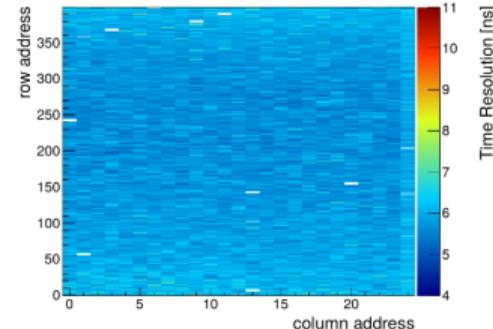
MuPix8 AMS 180nm 80 $\Omega\text{cm}$



MuPix8

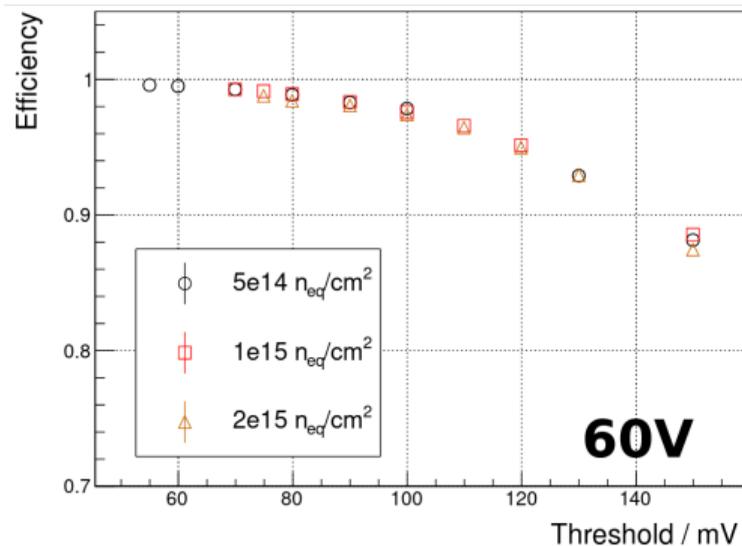
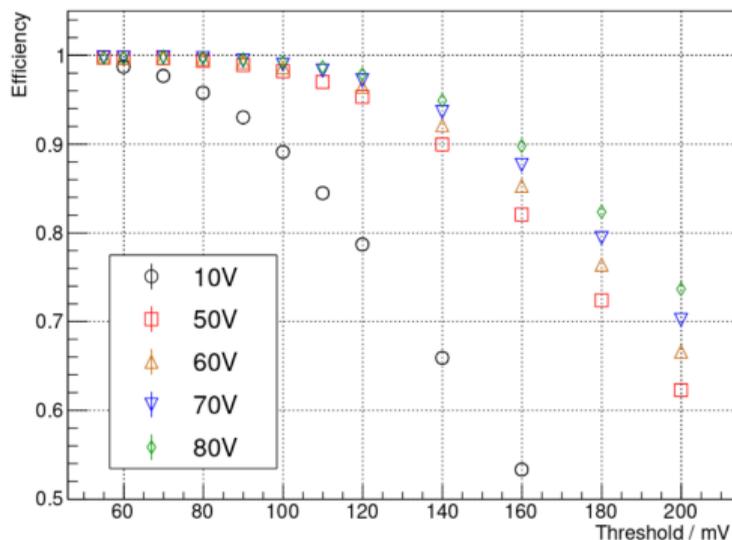


ATLASpix\_simple



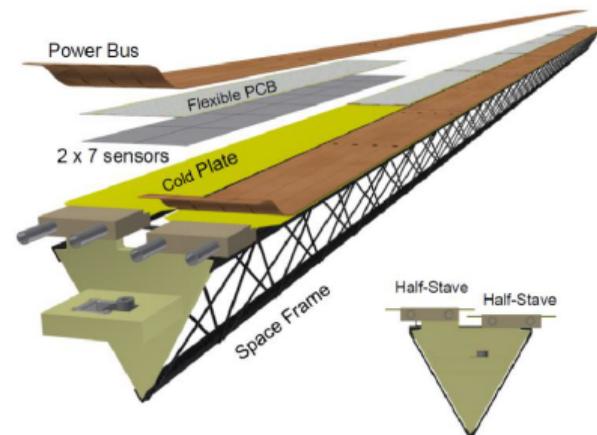
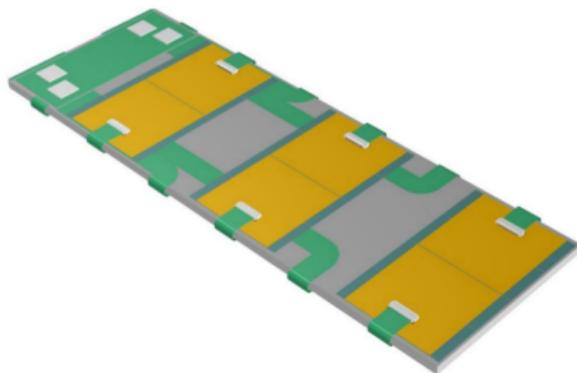
ATLASpix\_simple\_iso

- ATLASPix radiation tolerant at higher fluence than required.

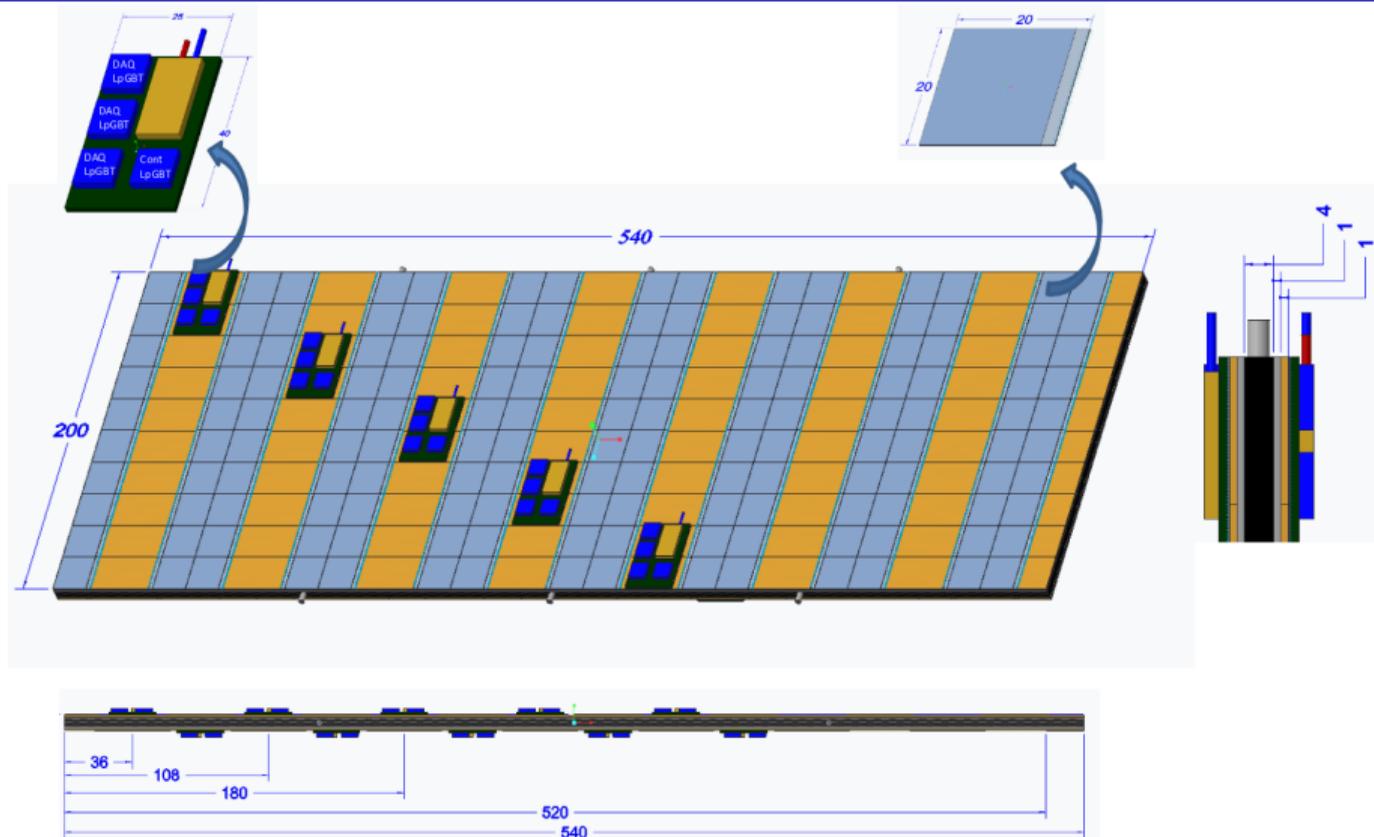


ATLASPix1 AMS 180nm 80Ωcm

- Design inspired in ATLAS ITk and ALICE inner tracker.
- Light carbon fiber structure for sensor and cooling system.
- Structure embeded in SciFi module, alternative for empty layers required.



- Service access planned vertically integrated or on top of SciFi module.
- Cooling 200W per module with  $\sim 15^{\circ}\text{C}$  water extrapolating from ATLAS ITk  $\sim 3\text{l}/\text{min}$ .
- First DAQ estimations yield 200 fibers.



**Thanks a lot for your attention!**